

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in this application:

**LISTING OF THE CLAIMS:**

1-11. (Canceled).

14. (Currently Amended) A device of a control unit, which is of a motor vehicle, having a circuit substrate that is stimulated by vibration during operation for providing a shakeproof accommodation of at least one of an electrical special component and an electrical circuit, comprising:

a carrier onto which [[a]] the circuit substrate having the special component fastened thereon is mounted in an electrically insulated manner at least over a partial surface so as to provide static and dynamic stability in a vibration-damping manner.

15. (Currently Amended) The device as recited in claim 14, further comprising:

an electrically insulating medium provided between the carrier and the circuit substrate.

16. (Previously Presented) The device as recited in Claim 14, wherein the circuit substrate is fastened to the carrier by one of a heat-dissipating adhesive, a laminated-on adhesive foil, screws, rivets and crimping.

17. (Previously Presented) The device as recited in claim 14, wherein the circuit substrate includes one of a printed-circuit board, a flex foil, a ceramic, and a wire harness.

18. (Previously Presented) The device as recited in claim 14, wherein the carrier has passages for contact pins that pass through.

19. (Currently Amended) The device as recited in claim 14, wherein the circuit substrate fastened to the carrier is able to be connected to [[a]] the control unit via pins.

20. (Previously Presented) The device as recited in claim 19, wherein the pins include one of a pin strip, SMD pins, punched bent parts, and male pin connectors.

21. (Previously Presented) The device as recited in claim 20, wherein the pin strip is situated on a tab, of the circuit substrate, which protrudes outwards over the carrier.

22. (Previously Presented) The device as recited in claim 20, wherein each pin strip is pressed into the circuit substrate.

23. (Previously Presented) The device as recited in claim 20, wherein the SMD pins are soldered onto the circuit substrate and extend downwards via lateral edges of the carrier to connect to a main board.

24. (Previously Presented) The device as recited in claim 14, wherein the circuit substrate fastened to the carrier is able to be connected to the control unit via a flex foil and a plug connection.

25. (Previously Presented) The device as recited in claim 14, wherein the carrier has screw openings for a passage of especially fastening screws that are able to be screwed into a floor of a control unit.

26. (Previously Presented) The device as recited in claim 14, wherein the carrier is made of cast aluminum.

27. (Currently Amended) The device as recited in claim 14, wherein the shakeproof accommodation is in a development as a second component set for ~~[[a]]~~ the control unit.

28. (New) The device as recited in claim 14, wherein the capacitor holder has a concave surface used to fasten the special component when the special component is a capacitor.